



SOD123F Rectifier

Material Content Declaration					
Material name	Substance name e.g. Copper (Cu), Gold (Au)	CAS no., if known	Substance mass (mg)	% OF Weight (%)	PPM Of Total Weight
Lead Frame 24.41%	Copper (Cu)	7440-50-8	4.34400	99.9617	243803.0
	Phosphorus (P)	7723-14-0	0.00007	0.0016	3.9
	Arsenic (As)	7440-38-2	0.00008	0.0018	4.5
	Tin (Sn)	7440-31-5	0.00008	0.0018	4.5
	Oxygen (O)	7782-44-7	0.00004	0.0009	2.2
	Sulfur (S)	7704-34-9	0.00095	0.0220	53.5
	Iron (Fe)	7439-89-6	0.00005	0.0012	2.9
	Nickel (Ni)	7440-02-0	0.00002	0.0006	1.3
	Bismuth (Bi)	7440-69-9	0.00015	0.0035	8.5
	Antimony (Sb)	1309-64-4	0.00016	0.0037	8.9
	Lead (Pb)	7439-92-1	0.00003	0.0008	1.8
	Zinc (Zn)	7440-66-6	0.00002	0.0006	1.3
	Total			4.35	
Solder Wafer 6.18%	Lead (Pb)	7439-92-1	1.018	92.50	57,106.2
	Tin (Sn)	7440-31-5	0.055	5.00	3086.8
	Silver (Ag)	7440-22-4	0.028	2.50	1543.4
	Total			1.10	
Chip 3.37%	Silicon (Si)	7440-21-3	0.602	100.00	33,758.6
	Total			0.60	
Molding 58.67%	Silica (SiO ₂)	14808-60-7	7.744	74.11	434,652.6
	Epoxy resin	29690-82-2	1.777	17.00	99,704.4
	Phenolic resin	9003-35-4	0.920	8.80	51,611.7
	Phosphorus(P)	7723-14-0	0.005	0.05	293.2
	Carbon Black	1333-86-4	0.004	0.04	234.6
	Total			10.45	
Plating 7.37%	Tin (Sn)	7440-31-5	1.323	100.00	74,252.1
	Total			1.32	
	Total mass (mg)		17.82		